BAND-GEM demonstrator

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The BAND-GEM team

DETECTING THERMAL NEUTRONS WITH GEMS

• Gas Electron Multiplier (GEM) detectors used for tracking and triggering applications (detection of charged particles)....

GEM advantages

- High rate capability (up to MHz/mm²)
- Submillimetric space resolution (suited to experiment requirements)
- Time resolution as short as 5 ns (gas mixture dependent)
- Can be realized in large areas (~ m²) and in different shapes
- Radiation hardness
- Low sensitivity to gamma rays (depends on threshold)
- Need a converter to detect neutrons.
 - ¹⁰Boron converter: ¹⁰B(n, α)⁷Li
- Converter-dominated performance limitation: ongoing R&D
- Need specific read-out (new ASIC chip)

OUTLINE

• THE BAND-GEM DETECTOR

- Principle of operation
- Simulation of detector performance

• APPLICATION @ LOKI

• LOKI Demonstrator



First Prototype Performance (Highlights)



VGEM = 980 *V*

BAND-GEM detector for neutron diffraction measurements



BAND-GEM application @ LOKI

Illustrative LOKI vessel Configuration



Requirements for rear detector panel
Peak rate Capability = 200 kHz/cm²

- •Time resolution better than 1 ms
- •Efficiency of about 60% at 4 Å
- •X-Y Space resolution of about 4 mm

BAND-GEM demonstrator for LOKI: one octant of rear detector panel





Inside-out is better...







Neutron absorption probability



 $\vartheta = 3.7^{\circ}$

Effective resolution across lamellas



Electron extraction – ANSYS field maps





Charge extraction simulations (1/2)



Boron strips on top of Ti/Al

charge from the lamella system

the drift lines

Charge extraction simulations (2/2)

OLD SIMULATION Prototype

NEW SIMULATION Demonstrator



IDL&Garfield++ Simulation taking into account the real absorption point of the neutrons



Performance: Prototype and Demonstrator

	Prototype - Achieved	Demonstrator - Projected
Lamella Distance	2 mm	4 mm
B ₄ C/empty ratio on lamellas	1	3
Full Lamella System length	6 cm	9 cm
Lamella Thickness	250 μm	20 µm
Lamella Material	Aluminium Oxide	Titanium
Optimal tilt angle	7 degrees	5 degrees
Pulse Height Threshold	70 keV	120 keV
Cathode geometry	10x10 cm2 - Square	Triangle (Trapezoidal)
Count Rate Capability	10 MHz/cm ²	12 MHz/cm ²
Gamma Ray Sensitivity	5*10 ⁻⁵	<5 10-7
Measured Efficiency @ 1.5 Å	18.5%	
Expected Efficiency @ 1.8 Å	21.2%	33%
Expected Efficiency @ 4 Å	49%	64%
Front-end ASIC	CARIOCA – 8 channels/chip	GEMINI – 16 (32) channels/ chip

The BAND-GEM demonstrator



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Cathode

Detector Assembly – The cake

Lamellae system

Each lamella is composed by a glass frame, 24 titanium strips and two glass columns.

Lamellae system: production method

- Ti foil (25 µm thick) coated with enriched B₄C
- Glass Frame is glued on top
- Strips are laser cut
- Lamella is ready

GEM Foil

The GEM foils will be realized at CERN and they will be glued to their frames using the same technique used for the production of the cathode.

Each GEM foil will be sectorized in 8 sectors, in order to reduce the possible damage caused by a spark. A total of 3 GEM (triple GEM) will be installed in the detector and the gap between each GEM (Transfer gaps) is equal to 2mm. All the GEM foils will be sandwiched and glued on the upper trapezoidal frame.

Padded Anode

1024 pads. Pad height is 4mm. Pad size between 7.7 and 137 mm². (Maximum pad size already tested)

Anode will be glued on the GEM3 frame

Gap between the GEM3 and the PADs (induction gap) will be 2mm.

Small Area version

Needed in order to test the construction technology and validate simulations Active area=10x10 cm².

The Front End Electronics

The first protoype electronics is based on Carioca Chip. Total dimension : 3x6 cm²

Digital Chip with 8 channels Equips the LHCb GEM detectors Fast chip – used for triggering Adapted from MWPC

A new chip is under development: the GEMINI chip. Mixed analog and digital chip with 16 channels/chip. Especially developed for GEM detectors

Conclusions

- First BANDGEM prototype successfully tested as neutron diffractometer
- BAND-GEM demonstrator for LOKI
 - Higher efficiency
 - New chip under design
 - Small area version available in May
 - Full size version available in September